



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Kinsman et al.

**Serial No.:** 10/624,833

**Filed:** July 22, 2003

**For:** METHOD FOR FABRICATING A  
CHIP SCALE PACKAGE USING WAFER  
LEVEL PROCESSING (as amended)

**Confirmation No.:** 6568

**Examiner:** M. Estrada

**Group Art Unit:** 2823

**Attorney Docket No.:** 2269-3572.2US  
(97-1243.02/US)

**Notice of Allowance Mailed:**

November 19, 2004

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**Person making Deposit:** Steve Wong

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Title** appear on page 3 of this paper.

**Amendments to the Specification** begin on page 4 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 8 of this paper.

**Amendments to the Drawings** appear on page 11 of this paper and include both attached replacement sheets and annotated sheets showing changes.

**Remarks** begin on page 12 of this paper.

An **Appendix** including amended drawing figures is attached following page 12 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**METHOD FOR FABRICATING A CHIP SCALE PACKAGE USING  
WAFER LEVEL PROCESSING ~~AND DEVICES RESULTING THEREFROM~~**